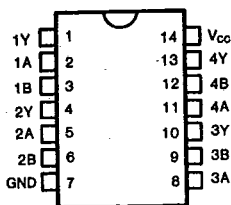


FEATURES

- Function, pin-out, speed and drive compatibility with 54/74LS logic family
- Low power consumption characteristic of CMOS
- High-Drive-Current outputs:
 $I_{OL} = 8\text{mA} @ V_{OL} = 0.5\text{V}$
- Inputs and outputs interface directly with TTL, NMOS and CMOS devices
- Wide operating voltage range: 4.5V to 5.5V
- Characterized for operation over industrial and military temperature ranges:
KS74HCTLS: -40°C to $+85^{\circ}\text{C}$
KS54HCTLS: -55°C to $+125^{\circ}\text{C}$
- Package options include plastic "small outline" packages, standard plastic and ceramic 300-mil DIPs

PIN CONFIGURATION



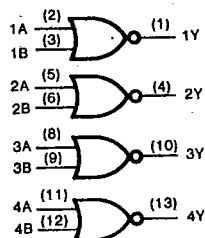
DESCRIPTION

These devices contain four independent 2-input NOR gates that perform the Boolean functions $Y = \overline{A+B}$ or $Y = \overline{A} \cdot \overline{B}$.

These devices provide speeds and drive capability equivalent to their LSTTL counterparts and yet maintain CMOS power levels. The input and output voltage levels allow direct interface with TTL, NMOS and CMOS devices without any external components.

All inputs and outputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

LOGIC DIAGRAM



FUNCTION TABLE

(Each Gate)

Inputs		Output
A	B	Y
H	X	L
X	H	L
L	L	H



Absolute Maximum Ratings*

Supply Voltage Range V_{CC} $-0.5V$ to $+7V$
 DC Input Diode Current, I_{IK}
 ($V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$) ± 20 mA
 DC Output Diode Current, I_{OK}
 ($V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$) ± 20 mA
 Continuous Output Current Per Pin, I_O
 ($-0.5V < V_O < V_{CC} + 0.5V$) ± 35 mA
 Continuous Current Through
 V_{CC} or GND pins ± 125 mA
 Storage Temperature Range, T_{stg} $-65^\circ C$ to $+150^\circ C$
 Power Dissipation Per Package, P_d † 500 mW

* Absolute Maximum Ratings are those values beyond which permanent damage to the device may occur. These are stress ratings only and functional operation of the device at or beyond them is not implied. Long exposure to these conditions may affect device reliability.

† Power Dissipation temperature derating:

Plastic Package (N): $-12mW/^\circ C$ from $65^\circ C$ to $85^\circ C$
 Ceramic Package (J): $-12mW/^\circ C$ from $100^\circ C$ to $125^\circ C$

Recommended Operating Conditions

Supply Voltage, V_{CC} $4.5V$ to $5.5V$
 DC Input & Output Voltages*, V_{IN} , V_{OUT} . . $0V$ to V_{CC}
 Operating Temperature
 Range KS74HCTLS: $-40^\circ C$ to $+85^\circ C$
 KS54HCTLS: $-55^\circ C$ to $+125^\circ C$
 Input Rise & Fall Times, t_r , t_f Max 500 ns
 * Unused inputs must always be tied to an appropriate logic voltage level (either V_{CC} or GND)

DC ELECTRICAL CHARACTERISTICS ($V_{CC}=5V \pm 10\%$ Unless Otherwise Specified)

Characteristic	Symbol	Test Conditions	T _a = 25°C		KS74HCTLS	KS54HCTLS	Unit
					T _a = -40°C to +85°C	T _a = -55°C to +125°C	
			Typ	Guaranteed Limits			
Minimum High-Level Input Voltage	V _{IH}			2.0	2.0	2.0	V
Maximum Low-Level Input Voltage	V _{IL}			0.8	0.8	0.8	V
Minimum High-Level Output Voltage	V _{OH}	V _{IN} =V _{IH} or V _{IL} I _O =-20μA I _O =-4mA	V _{CC} 4.2	V _{CC} -0.1 3.98	V _{CC} -0.1 3.84	V _{CC} -0.1 3.7	V
Maximum Low-Level Output Voltage	V _{OL}	V _{IN} =V _{IH} or V _{IL} I _O =20μA I _O =4mA I _O =8mA	0	0.1 0.26 0.39	0.1 0.33 0.5	0.1 0.4	V
Maximum Input Current	I _{IN}	V _{IN} =V _{CC} or GND		±0.1	±1.0	±1.0	μA
Maximum Quiescent Supply Current	I _{CC}	V _{IN} =V _{CC} or GND I _{OUT} =0μA		2.0	20.0	40.0	μA
Additional Worst Case Supply Current	ΔI _{CC}	per input pin V _I =2.4V other Inputs: at V _{CC} or GND I _{OUT} =0μA		2.7	2.9	3.0	mA

AC ELECTRICAL CHARACTERISTICS (Input t_r , $t_f \leq 6$ ns), HCTLS02

Characteristic	Symbol	Conditions†	T _a = 25°C V _{CC} = 5.0V		KS74HCTLS T _a = - 40°C to + 85°C V _{CC} = 5.0V ± 10%		KS54HCTLS T _a = - 55°C to + 125°C V _{CC} = 5.0V ± 10%		Unit
			Typ		Guaranteed Limits				
			9	15	18	22			
Maximum Propagation Delay	t _{PLH}	C _L = 50pF	10	15	18	22	ns		
	t _{PHL}		10	15	18	22			
Maximum Input Capacitance	C _{IN}		5				pF		
Power Dissipation Capacitance*	C _{PD}	(per gate)	15				pF		

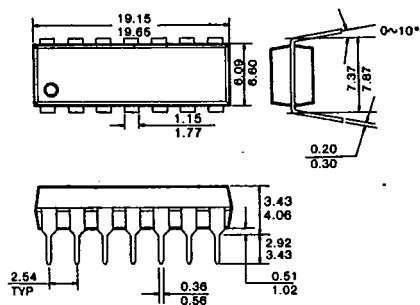
* C_{PD} determines the no-load dynamic power dissipation: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$

† For AC switching test circuits and timing waveforms see section 2.

1. PLASTIC PACKAGES

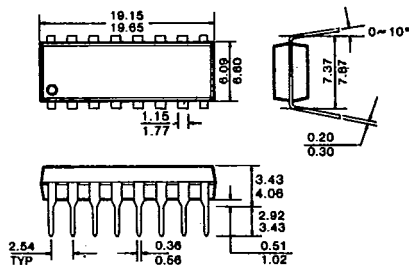
14-Pin Plastic DIP

Units: mm



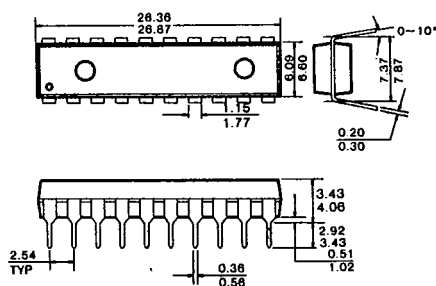
16-Pin Plastic DIP

Units: mm



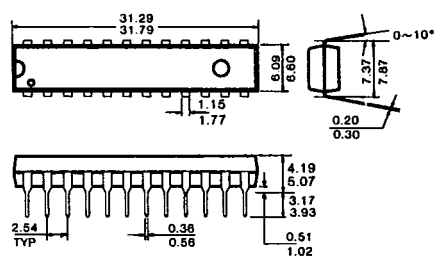
20-Pin Plastic DIP

Units: mm



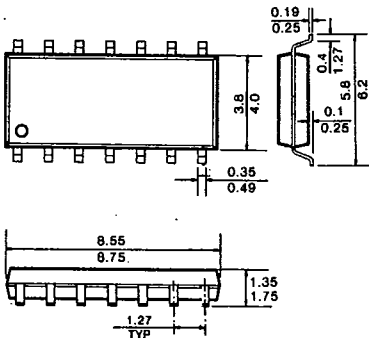
24-Pin Plastic DIP

Units: mm



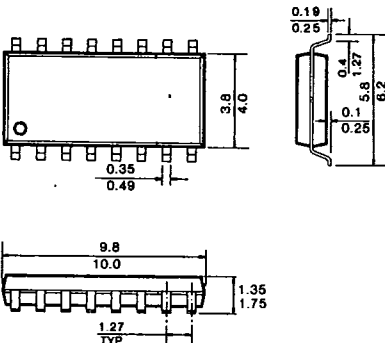
14-Pin SOP

Unit: mm



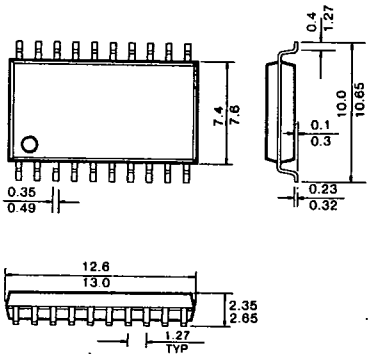
16-Pin SOP

Unit: mm



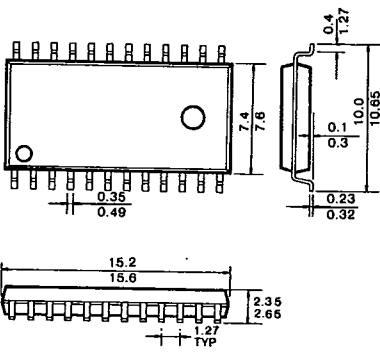
20-Pin SOP

Unit: mm



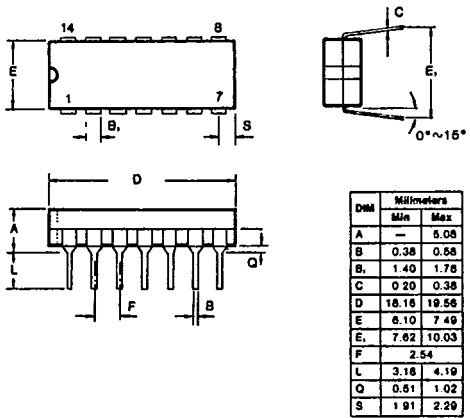
24-Pin SOP

Unit: mm

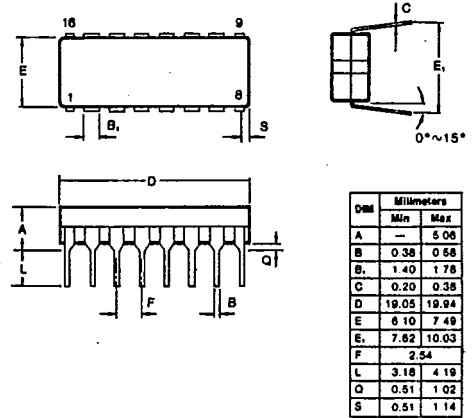


2. CERAMIC PACKAGES

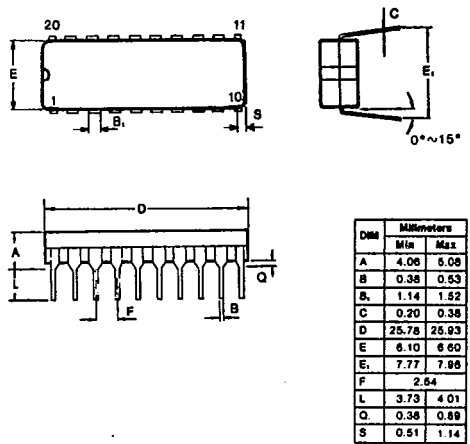
14-Pin Ceramic DIP Units: mm



16-Pin Ceramic DIP Units: mm



20-Pin Ceramic DIP Units: mm



24-Pin Ceramic DIP Units: mm

